Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	2	("5864177" | "6005778").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/16 14:31
L3	1615	257/777.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:32
L4	3	("4132856" | "4809053" | "5631497").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/16 14:34
L5	14	("5804872").URPN.	USPAT	OR	ON	2005/09/16 14:34
L7	2535	257/718-720.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:52
L8	1711	7 and (substrate or board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:41
L9	1259	7 and ((circuit adj substrate) or board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:39
L11	1246	9 not 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:39
L12	1380	257/796,675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:39
L13	1153	11 not L12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:40
L15	2375	257/712.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 15:21

L16	963	15 and ((chip or die) with heat)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:53
L17	821	16 and (substrate or board or PCB)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 15:21
L18	1554	15 not 17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 15:05
L19	2341	257/705-707.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 15:21
L20	1930	19 and (substrate or board or PCB)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 15:22
L21	1805	20 and heat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 15:55
L22	536	19 not 21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 16:01
L23	5477	(chip or die) near (stack or stacked or stacking)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 16:02
L24	354	23 with heat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 16:02
L29	2	"20040156173"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 16:23

S1	4723	heat adj spreader	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:30
S2	2940	S1 and (chip or semiconductor) and packag$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:12
S3	146	(epoxy adj mold adj compound)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:32
S4	14	S2 and S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:46
S5	1380	257/796,675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 19:32
S6	1199	S5 and (heat)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:47
S7	757	S6 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:47
S8	136	S7 and S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:47
S9	121474	(chip or semiconductor) with (package or packaging)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:14
S10	1796	S9 and (chip near3 stack)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:14

S11	129678	(chip or semiconductor or die) with (package or packaging)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:14
S12	3075	S9 and ((chip or die) with stack)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:14
S13	987	S12 and ((chip or die) with heat)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:14
S14	192	S13 and PCB	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:22
S15	13	"6242285"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:04
S16	12602	(die or chip) with (die or chip) with (heat adj (sink or spreader))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:05
S17	126	S16 and ((second or upper or top) adj (pCB or (circuit adj board)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:06
S18	1	Jeong near (Nyeon$1Sik)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:20
S19	1	Jeong near2 Nyeon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:21
S20	1	Jeong near3 Nyeon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:21

S21	760210	package or packaging	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:23
S22	7434	S21 and ((stack or stacked) with (die or chip))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:23
S23	1524	(upper or top) adj ((printed adj circuit) or PCB)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:26
S24	5497	(second or first or upper or top) adj ((printed adj circuit) or PCB)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:26
S25	4592	S24 and (second or first or lower or bottom) adj ((printed adj circuit) or PCB)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:27
S26	39	S22 and S25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 18:27
S27	1615	257/777.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:32